AMENDMENT UNDER 37 C.F.R. 1.116 - EXPEDITED PROCEDURE

Serial Number: 09/964586

Filing Date: September 28, 2001

Title: ARRANGEMENTS TO SUPPLY POWER TO SEMICONDUCTOR PACKAGE

Assignee: Intel Corporation

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IN THE SPECIFICATION

Please amend the paragraph beginning at page 6, line 1 as follows:

Reference is made to patent application entitled "Arrangements To Increase Structural Rigidity of Semiconductor Package Heat Spreader and Stiffener Having A Stiffener Extension (as amended)" by inventors Hong Xie, Kristopher Frutschy, Koushik Banerjee, and Ajit Sathe filed on a same date as the filing of this patent application September 28, 2001 and published on April 3, 2003, having Application No. 9/964494, and Publication No. US-2003-0062618-A1.